P26634.A13

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Chuen Khiang WANG et al. Confirmation No. 6698

Appl. No.: 10/598,514 Examiner: Ahmed, S. U.

(U.S. National Stage of PCT/SG2005/00067)

I.A. Filed: March 3, 2005 Group Art Unit: 2826

For : MULTIPLE STACKED DIE WINDOW CSP PACKAGE AND METHOD

OF MANUFACTURE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria. VA 22314

Sir:

In accordance with the duty of disclosure under 37 CFR \S 1.56 and $\S\S$ 1.97 – 1.98, Applicants wish to bring the following information to the attention of the Examiner.

Applicants wish to make of record the documents listed on the attached form PTO-1449. Copies of the listed documents are attached, where required, as are noted English translations, or partial translations of pertinent portions, and/or English language abstracts, of any non-English language references. Statements of relevancy, if necessary, appear below.

COMMONLY ASSIGNED

□ Listed on the attached form PTO-1449 are certain of Applicant's commonly assigned pending application(s), published application(s) or issued patent(s). In accordance with 37 CFR §1.98(a)(2)(ii), copies of the cited U.S. pending applications, published applications and/or issued patents, are not provided.

STATEMENT OF RELEVANCY

- Documents * * have been cited in an International Search Report and/or Written Opinion, which indicates the relevancy thereof to the claims of the International Application. Copies of documents cited in the International Search Report should have been forwarded by the International Bureau and thus have not been provided.
- U.S. 2003/0197284 and U.S. 2002/0027295 have been cited in the corresponding Taiwanese Office Action dated October 1, 2010, which indicates the relevancy of the cited documents. Copies of the Taiwanese Office Action and a partial English language

P266	34.A13 translation are being submitted herewith.
	Documents * * are cited in the Specification of the present application. Any necessary copy is being submitted herewith.
	Documents * * have been cited in the parent application(s) either by the Applicant(s) or by the examiner. Copies of these documents should be available in the parent application(s) and thus have not been provided herewith.
	Documents * * are related as patent family members.
	Documents * * were cited in related U.S. Patent Application No
	Documents * * were cited by a third party.
	Documents * were previously cited in an earlier filed Information Disclosure Statement in the present application.
	Miscellaneous.
CERT	TIFICATION
	Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement. This certification does not apply to any document previously cited in the present application.
	Moreover, this communication was not received by any individual designated in $\S1.56$ (c) more than thirty days prior to the filing of the Information Disclosure Statement.
FEES	
	A payment in the amount required under 37 CFR §1.17(p) is provided herewith.
DEPO	OSIT ACCOUNT
	In the event that any additional fees are due with respect to this paper, the Commissioner is hereby authorized to charge such fees to Deposit Account No. ****** of the undersigned
number	If there should be any questions, the Examiner is invited to contact the undersigned at the telephone listed below. Respectfully submitted,
	Clauen Khiang WANG et al. August H. Bernstein Reg. #47,348
	Reg. No. 29027
GREE 1950 F Restor	er 29, 2010 NBLUM & BERNSTEIN, P.L.C. Roland Clarke Place 1, VA 20191 716-1191